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PATENT APPLICATION

#13160E
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q62228

Yoshihisa FURUTA, et al.

Appln. No.: 09/719,422

Group Art Unit: 1733

Confirmation No.: 7788

Examiner: Barbara J. Musser

Filed: December 12, 2000

For: METHOD OF RESIN ENCAPSULATING SEMICONDUCTOR CHIP AND PRESSURE-SENSITIVE ADHESIVE TAPE FOR ADHESION TO LEADFRAME AND THE LIKE

RESPONSE UNDER 37 C.F.R. § 1.111

MAIL STOP NON-FEE AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In response to the Office Action dated April 24, 2003, please consider the remarks in the above-identified application as follows on the accompanying pages. Applicants concurrently file a petition for an extension of time of one month, extending the time for responding to the Office Action of April 24, 2003 to August 25, 2003, as August 24, 2003, falls on a Sunday.

REMARKS

Claims 1-5 are all the claims pending in the application.

Reconsideration and review of the claims on the merits are respectfully requested.